

ABSTRACT

The present invention provides a thermally curable resin sheet for sealing a semiconductor chip having excellent reliability and storability while being reduced in warpage deformation due to the volume shrinkage of the thermally curable resin sheet, and a method for manufacturing a semiconductor package. The present invention relates to a thermally curable resin sheet for sealing a semiconductor chip, wherein an activation energy (E_a) satisfies the following formula (1), a glass transition temperature of a product thermally cured at 150°C for 1 hour is 125°C or higher, and a thermal expansion coefficient α [ppm/K] of the thermally cured product at the glass transition temperature or lower and a storage modulus E' [GPa] at 25°C of the thermally cured product satisfy the following formula (2):

$$30 \leq E_a \leq 120 \text{ [kJ/mol]} \cdots (1); \text{ and}$$

$$10,000 \leq \alpha \times E' \leq 300,000 \text{ [Pa/K]} \cdots (2).$$